



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-02-24
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance\* true Legal declaration\* Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
TSL393IYQ3T	BNK9*V3931BY	A	Z3NA	2025-02-24
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	8.07	mg	Each	ECOPACK® 3
<b>Identity</b>	<b>Authority</b>			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
1	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape	
qfn	2x2	8	No lead	
Comment				
Comment	B045 WDFPN 2X2X0.8 8 P 0.5 WET FLK			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
<b>Exemption Id.</b>	<b>Description</b>	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
<b>Exemption Id.</b>	<b>Description</b>	

QueryList : California Prop65 list, dated 3rd January 2025				Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen				true
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen				false
<b>Substance</b>	<b>amount in product (mg)</b>	<b>Application</b>	<b>ppm in product</b>	
Nickel	0.000	alloy	0	

QueryList :Customer		Response
QUERY		Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014					Response
QUERY					Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products					false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products					false
<b>Hazardous substance</b>					
<b>Lead (Pb)</b>	<b>Cadmium (Cd)</b>	<b>Mercury (Hg)</b>	<b>Hexavalent Chromium (Cr VI)</b>	<b>PBB &amp; PBDE</b>	
O	O	O	O	O	

QueryList : REACH-21st January 2025					Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH					true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product	
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH					true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material	



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tin,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	BNK9*V3931BY		8.0703		6000000.0	1000041.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies or Wafer (choose)	M-011 Other inorganic materials	0.410	mg	supplier	die	Silicon(Si)	7440-21-3		0.391	mg	953659	48451
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.005	mg	12195	620
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	2439	124
				supplier	Passivation	Silicon nitride(Si)	12033-89-5		0.001	mg	2439	124
				supplier	passivation	Silicon oxide	7631-86-9		0.012	mg	29268	1487
Leadframe	M-004 Copper and its alloys	2.277	mg	supplier	alloy	Copper	7440-50-8		2.208	mg	969697	273606
				supplier	alloy	Iron	7439-89-6		0.052	mg	22837	6444
				supplier	alloy	Phosphorus	7723-14-0		0.001	mg	439	124
				supplier	alloy	Zinc	7440-66-6		0.003	mg	1318	372
				supplier	alloy	Silver	7440-22-4		0.013	mg	5709	1611
Die attach	M-011 Other inorganic materials	0.101	mg	supplier	glue	Epoxy Resin A	29690-82-2		0.007	mg	70000	876
				supplier	glue	Epoxy Resin B	9003-36-5		0.014	mg	140000	1752
				supplier	glue	Phenol Resin	9003-35-4		0.014	mg	140000	1752
				supplier	glue	SiO2 Filler	7631-86-9		0.051	mg	500000	6258
				supplier	glue	Acrylic Copolymer	58152-79-7		0.015	mg	150000	1877
Bonding wires	M-008 Precious metals	0.087	mg	supplier	wire	Au	7440-57-5		0.087	mg	1000000	10755
Encapsulation	M-011 Other inorganic materials	4.752	mg	supplier	mold compound	Epoxy Resin	Proprietary		0.302	mg	63479	37381
				supplier	mold compound	Phenol Resin	Proprietary		0.163	mg	34278	20186
				supplier	mold compound	Silica (Amorphous)	60676-86-0		3.968	mg	834955	491685
				supplier	mold compound	Silica (Amorphous)	7631-86-9		0.302	mg	63479	37381
Connections coating	Solder	0.443	mg	supplier	mold compound	Carbon Black	1333-86-4		0.018	mg	3809	2243
				supplier	solder alloy	Tin(Sn)	7440-31-5		0.443	mg	1000000	54932